

N-Channel Trench Power MOSFET

General Description

The CS60N06 is N-channel MOS Field Effect Transistor designed for high current switching applications. Rugged EAS capability and ultra low $R_{DS(ON)}$ is suitable for PWM, load switching applications.

Features

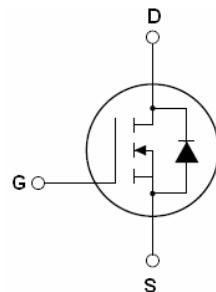
- $V_{DS}=60V$; $I_D=80A$ @ $V_{GS}=10V$;
 $R_{DS(ON)}<7.2m\Omega$ @ $V_{GS}=10V$
- Ultra Low On-Resistance
- High UIS and UIS 100% Test

Application

- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply



To-220 Top View



Schematic Diagram

$$V_{DS} = 60 \text{ V}$$

$$I_D = 80 \text{ A}$$

$$R_{DS(ON)} = 6.2 \text{ m}\Omega$$

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
CS60N06	CS60N06	TO-220	-	-	-

Table 1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	60	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 25	V
I_D (DC)	Drain Current (DC) at $T_c=25^\circ\text{C}$	80	A
I_D (DC)	Drain Current (DC) at $T_c=100^\circ\text{C}$	56	A
I_{DM} (pulse)	Drain Current-Continuous@ Current-Pulsed ^(Note 1)	320	A
dv/dt	Peak Diode Recovery Voltage	9.5	V/ns
P_D	Maximum Power Dissipation($T_c=25^\circ\text{C}$)	100	W
	Derating Factor	0.66	W/ $^\circ\text{C}$
E_{AS}	Single Pulse Avalanche Energy ^(Note 2)	410	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 175	$^\circ\text{C}$

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2.Es condition: $T_J=25^\circ\text{C}$, $V_{DD}=33V$, $V_G=10V$, $I_D=40.5A$

Table 2. Thermal Characteristic

Symbol	Parameter	Value	Max	Unit
$R_{\theta JC}$	Thermal Resistance,Junction-to-Case	---	1.5	°C/W

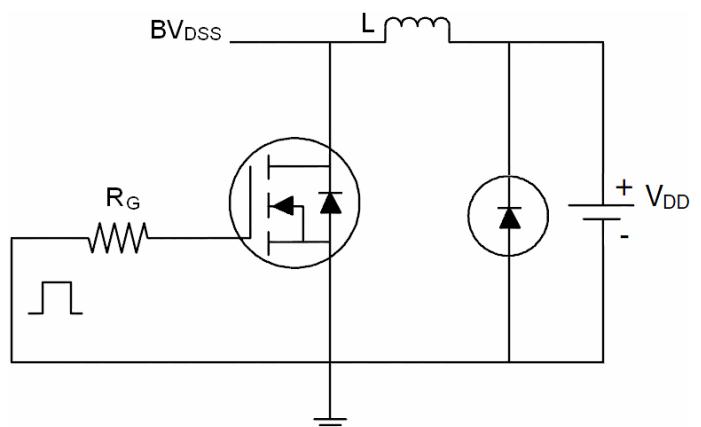
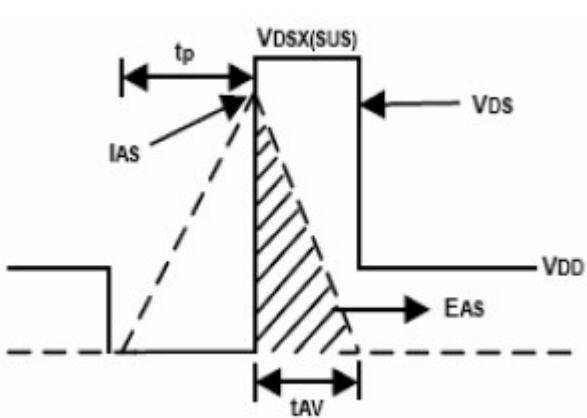
Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60			V
$I_{DS(on)}$	Zero Gate Voltage Drain Current($T_c=25^\circ C$)	$V_{DS}=60V, V_{GS}=0V$			1	μA
$I_{DS(on)}$	Zero Gate Voltage Drain Current($T_c=125^\circ C$)	$V_{DS}=60V, V_{GS}=0V$			10	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 25V, V_{DS}=0V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2		4	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=40A$		6.2	7.2	$m\Omega$
Dynamic Characteristics						
g_{FS}	Forward Transconductance	$V_{DS}=10V, I_D=15A$	20			S
C_{iss}	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1.0MHz$		3290		pF
C_{oss}	Output Capacitance			335		pF
C_{rss}	Reverse Transfer Capacitance			245		pF
Q_g	Total Gate Charge	$V_{DS}=50V, I_D=40A, V_{GS}=10V$		90		nC
Q_{gs}	Gate-Source Charge			18		nC
Q_{gd}	Gate-Drain Charge			42		nC
Switching Times						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=30V, I_D=2A, R_L=15\Omega$ $V_{GS}=10V, R_G=2.5\Omega$		21		nS
t_r	Turn-on Rise Time			31		nS
$t_{d(off)}$	Turn-Off Delay Time			63		nS
t_f	Turn-Off Fall Time			29		nS
Source-Drain Diode Characteristics						
I_{SD}	Source-Drain Current(Body Diode)			80		A
I_{SDM}	Pulsed Source-Drain Current(Body Diode)			320		A
V_{SD}	Forward On Voltage ^(Note 1)	$T_J=25^\circ C, I_{SD}=40A, V_{GS}=0V$		0.89	0.99	V
t_{rr}	Reverse Recovery Time ^(Note 1)	$T_J=25^\circ C, I_F=75A$ $di/dt=100A/\mu s$		26		nS
Q_{rr}	Reverse Recovery Charge ^(Note 1)			35		nC
t_{on}	Forward Turn-on Time	Intrinsic turn-on time is negligible(turn-on is dominated by L_s+L_D)				

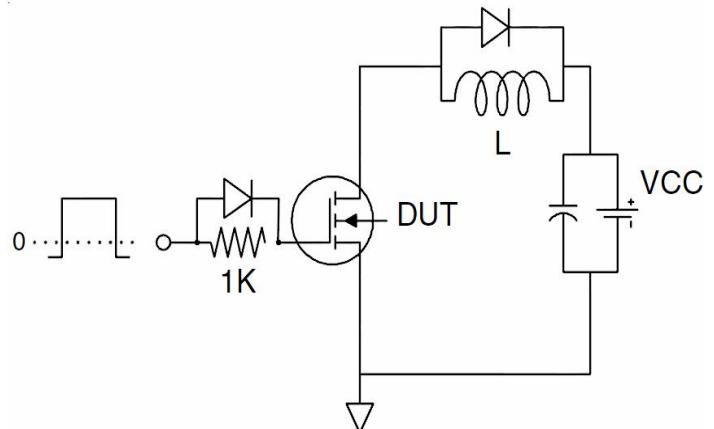
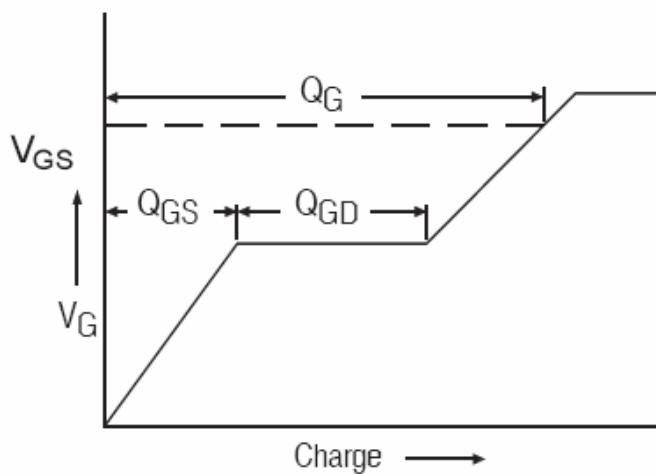
Notes 1.Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 1.5%, $R_G=25\Omega$, Starting $T_J=25^\circ C$

Test Circuit

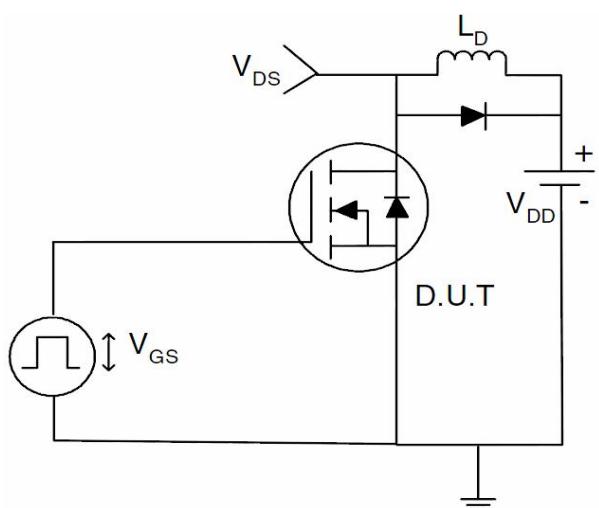
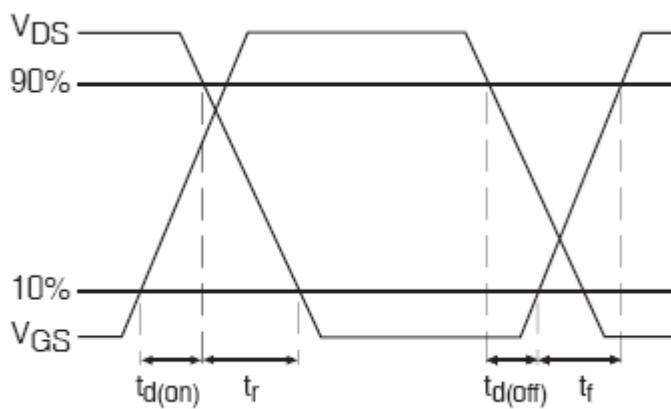
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit:



3) Switch Time Test Circuit:



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure1. Output Characteristics

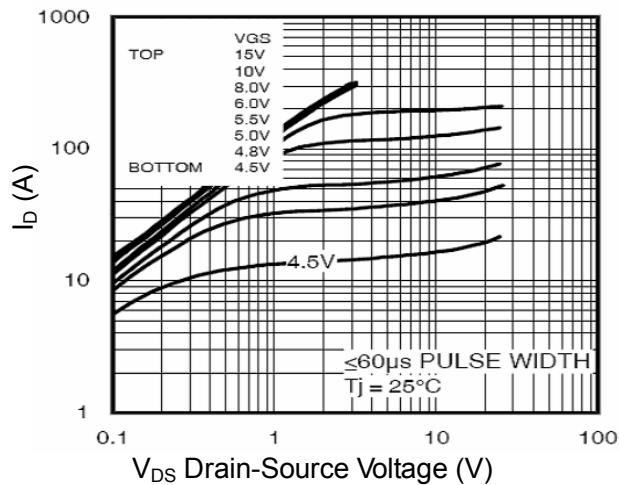


Figure2. Transfer Characteristics

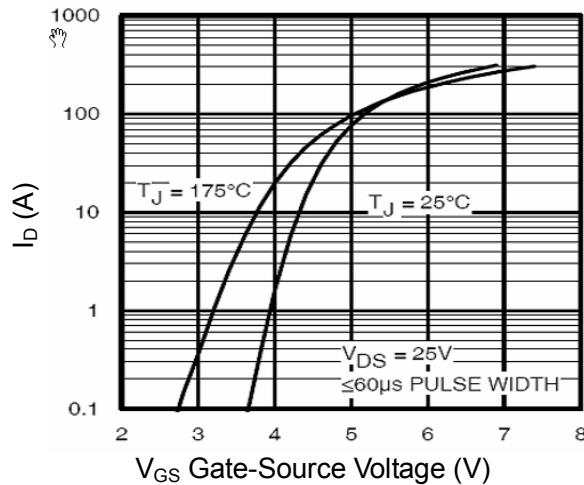


Figure3. BVDSS vs Junction Temperature

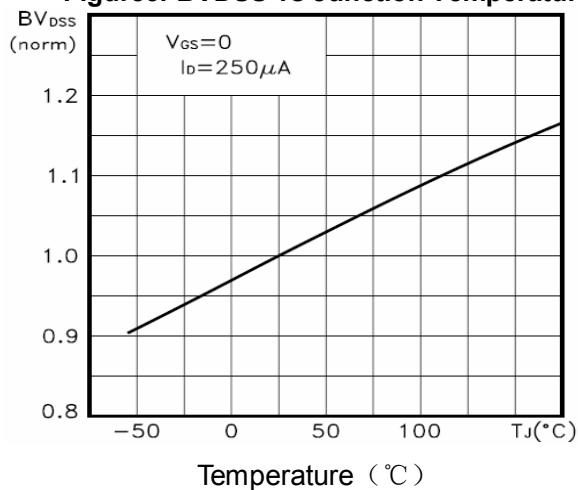


Figure4. ID vs Junction Temperature

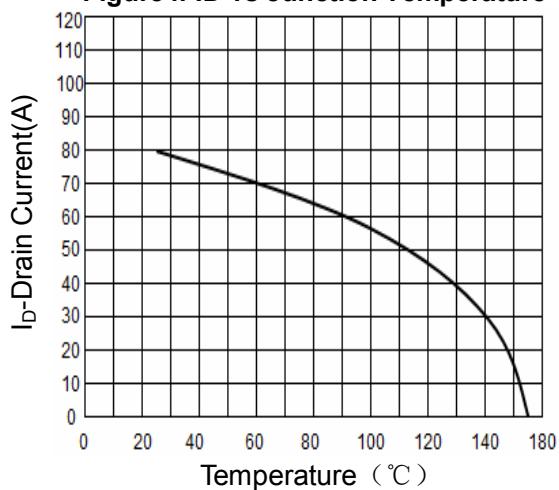


Figure5. $V_{GS(th)}$ vs Junction Temperature

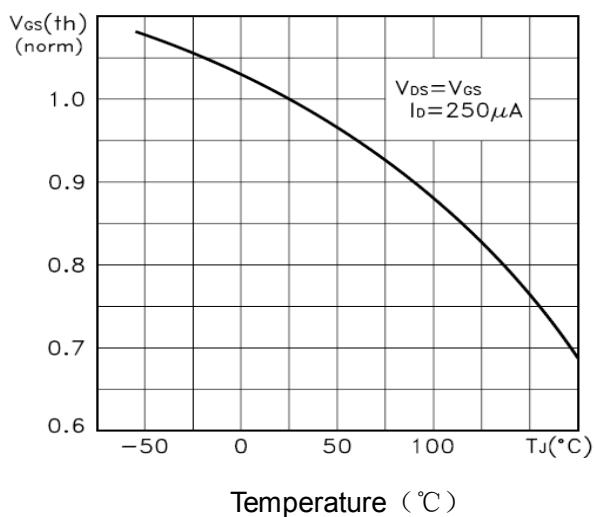


Figure6. Rdson vs Junction Temperature

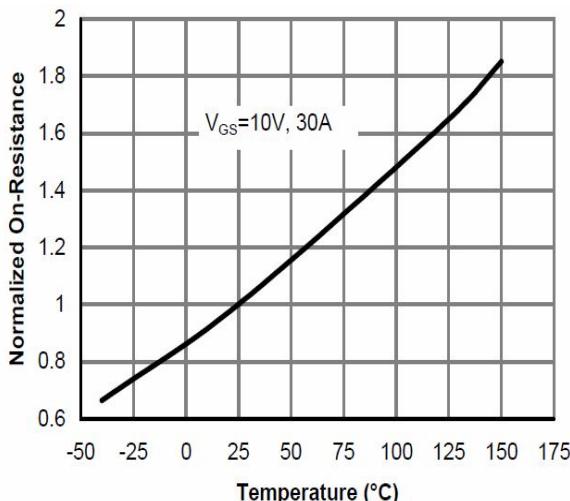


Figure7. Gate Charge

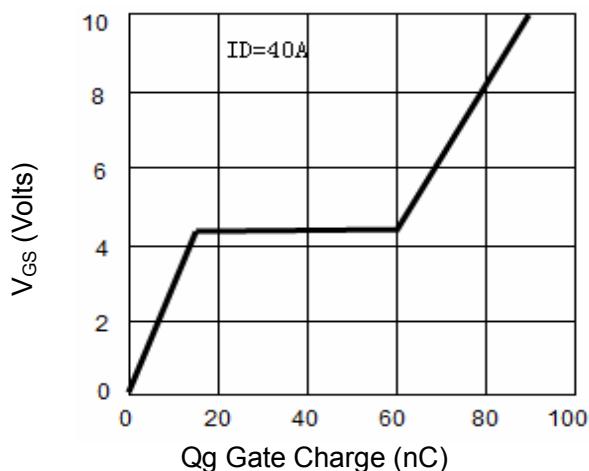


Figure8. Capacitance vs Vds

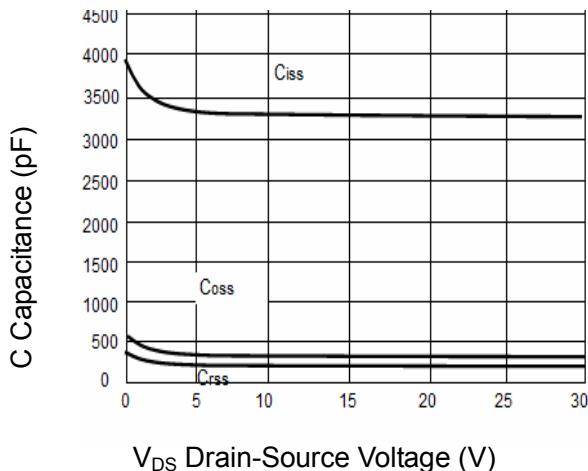


Figure9. Source- Drain Diode Forward

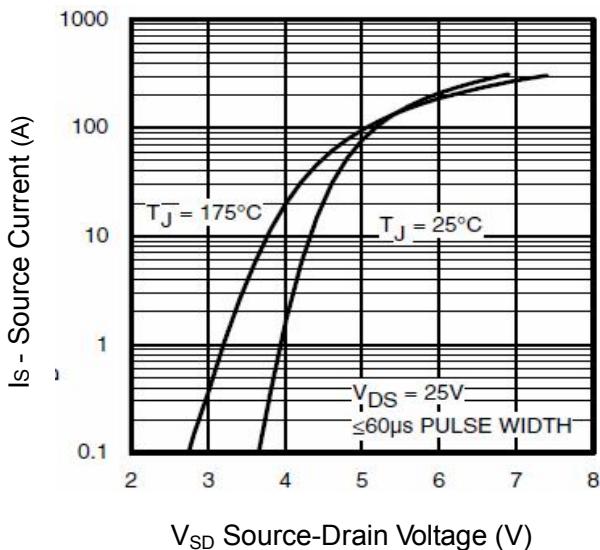


Figure10. Safe Operation Area

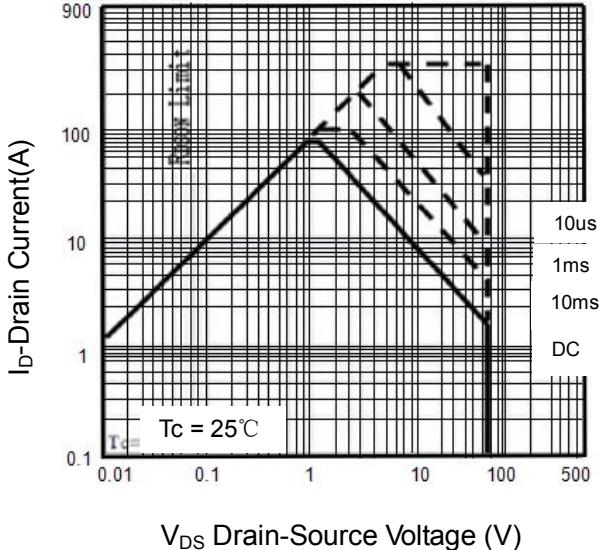
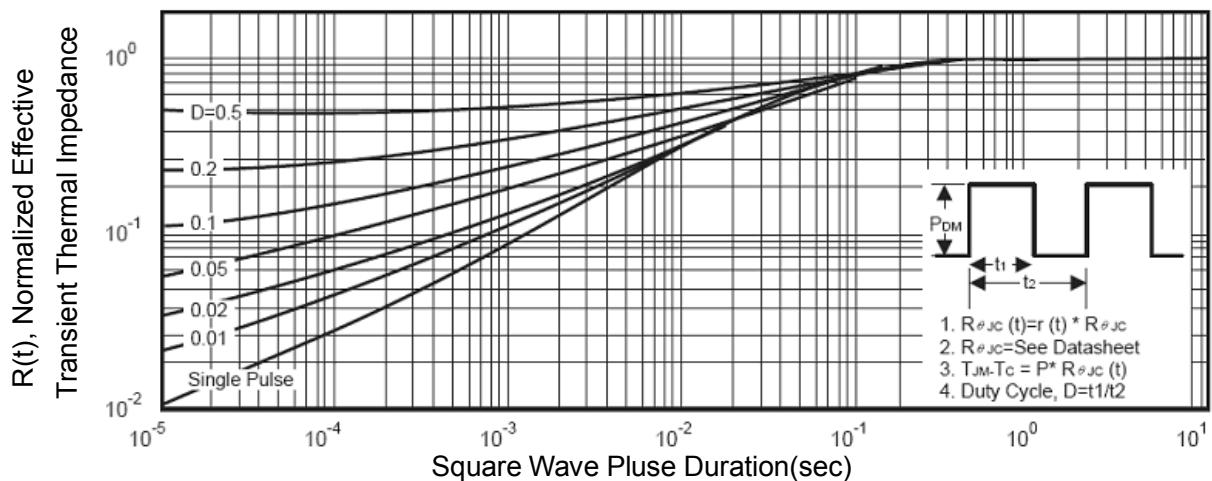
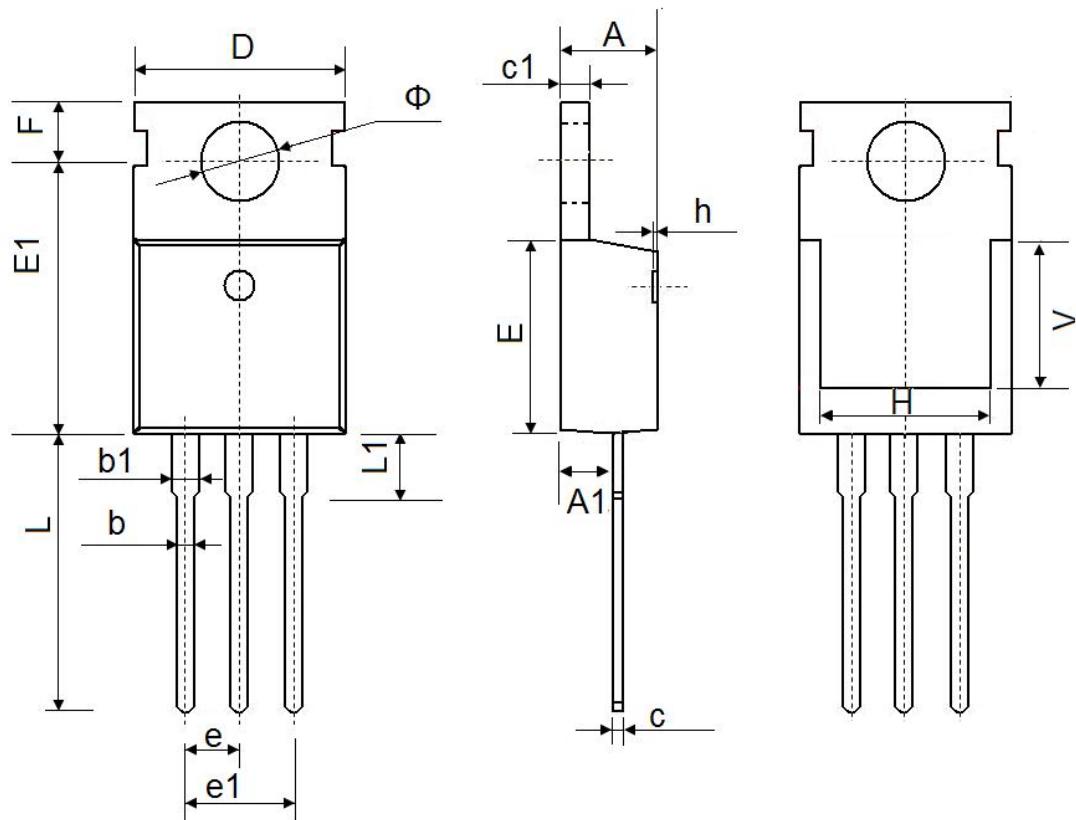


Figure11. Normalized Maximum Transient Thermal Impedance



TO-220 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.300	4.700	0.169	0.185
A1	2.200	2.600	0.087	0.102
b	0.700	0.950	0.028	0.037
b1	1.170	1.410	0.046	0.056
c	0.450	0.650	0.018	0.026
c1	1.200	1.400	0.047	0.055
D	9.600	10.400	0.378	0.409
E	8.8500	9.750	0.348	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.750	14.300	0.502	0.563
L1	2.850	3.950	0.112	0.156
V	7.500 REF.		0.295 REF.	
Φ	3.400	4.000	0.134	0.157